

Title (en)  
METHOD FOR COATING ELECTRICALLY CONDUCTIVE SUBSTRATES

Title (de)  
VERFAHREN ZUM BESCHICHTEN ELEKTRISCH LEITFÄHIGER SUBSTRATE

Title (fr)  
PROCEDE POUR ENDUIRE DES SUBSTRATS ELECTRIQUEMENT CONDUCTEURS

Publication  
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Application  
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Abstract (en)  
[origin: WO2005120724A1] The invention relates to a method for coating electrically conductive substrates during which: (1) an electrodeposition paint layer is applied to an electrically conductive substrate and is cured whereby resulting in the formation of an electro-dip coating; afterwards, (2) a layer consisting of a powdery coating material is applied to the electro-dip coating and is cured whereby resulting in the formation of a powder coating, or during which: alternatively, (1) an electrodeposition paint layer is applied to an electrically conductive substrate and, without it being completely cured, is dried; (2) a layer of a powdery coating material is applied to the dried electrodeposition paint layer(s), and; (3) the dried electrodeposition paint layer and the layer of the powdery coating material are cured together whereby resulting in formation of the electro-dip coating and the powder coating. The powdery coating material contains: (A) at least one epoxy resin having a melting point, a melting range or a glass transition temperature of > 30 DEG C; (B) at least one carboxyl group-containing polyester resin, which has a melting point, a melting range or a glass transition temperature of > 30 DEG C, and; (C) at least one polycarboxylic acid with a melting point ranging from 80 to 160 DEG C.

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